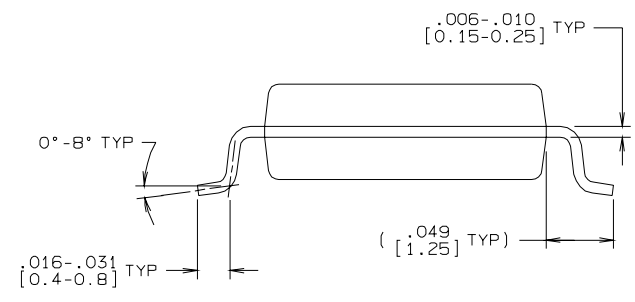
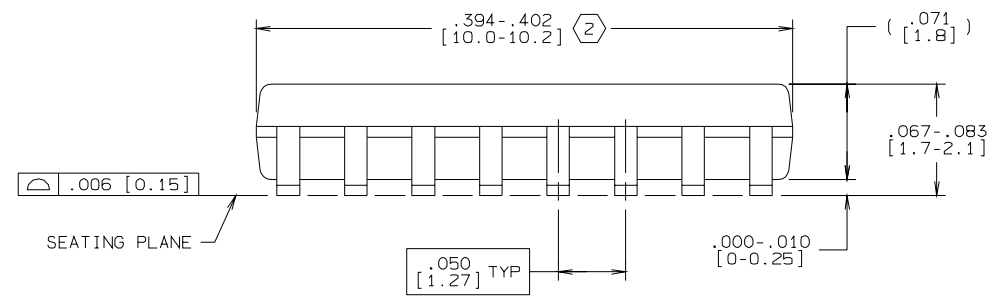
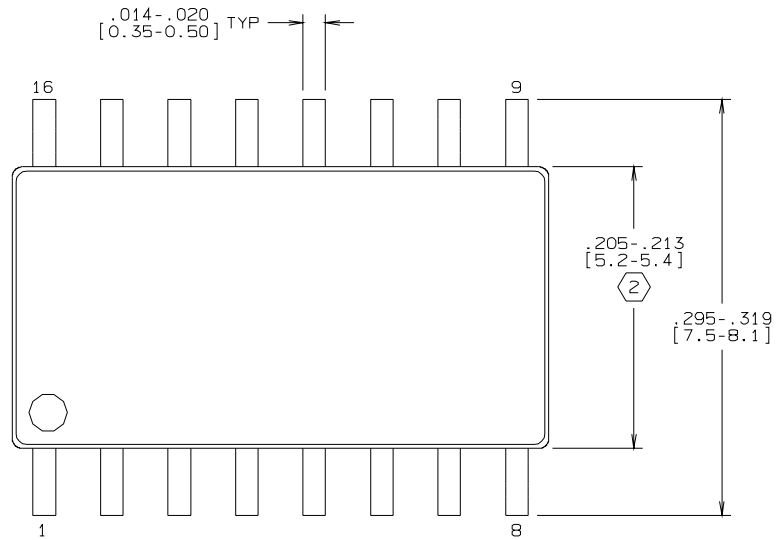


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	07669	07/27/90	DEG/CC
B	TITLE WAS: MOLDED PACKAGE EIAJ, 300 MIL SOP, 16 LEAD; ADD TYP TO SIDE VIEW DIM'S; REDRAW.	10212	01/04/94	MS/



COTROLLING DIMENSION: MILLIMETER

NOTES: UNLESS OTHERWISE SPECIFIED

- 1. SOLDER PLATED LEAD FINISH.
- (2) THESE DIMENSIONS DO NOT INCLUDE MOLD FLASH.

APPROVALS	DATE	NATIONAL SEMICONDUCTOR CORPORATION		
DRAWN MARTA SUCHY	01/04/94	2900 Semiconductor Drive, Santa Clara, CA 95052-8090		
DF TG. CHK.		MOLDED SOP, EIAJ TYPE II, 16 LEAD		
ENGR. CHK.				
APPROVAL				
PROJECTION	SCALE	SIZE	DRAWING NUMBER	REV
	N/A	C	MKT-M16D	B
DO NOT SCALE DRAWING		SHEET 1 OF 1		